# **Guided Tour**

# **Learning Features**

Many new learning features have been incorporated into the seventh edition of *Electronic Principles*. These learning features, found throughout the chapters, include:



## EXAMPLES

Each chapter contains worked-out Examples that demonstrate important concepts or circuit operation, including circuit analysis, applications, troubleshooting, and basic design.

## PRACTICE PROBLEMS

Students can obtain critical feedback by performing the Practice Problems that immediately follow most Examples. Answers to these problems are found at the end of each chapter.

## GOOD TO KNOW

Good To Know statements, found in the margins, provide interesting added insights to topics being presented.

## **MULTISIM** -

Students can "bring to life" many of the circuits found in each chapter. A CD containing MultiSim files is included with the textbook; with these files students can change the value of circuit components and instantly see the effects, using realistic Tektronix and Agilent simulation instruments. Troubleshooting skills can be developed by inserting circuit faults and making circuit measurements. Students new to computer simulation software will find a MultiSim Primer in the appendix.



Example 3-5 Use the second approxir diode power in Fig. 3-8. ion to calculate the load voltage, load current, an **SOLUTION** Since the diode is forward biased, it is equivalent to a battery 0.7 V. This means that the load voltage equals the source voltage minus the  $V_L = 10 \text{ V} - 0.7 \text{ V} = 9.3 \text{ V}$ With Ohm's law the load current is  $I_L = \frac{9.3 \text{ V}}{1 \text{ k}\Omega} = 9.3 \text{ mA}$  $P_{D} = (0.7 \text{ V})(9.3 \text{ mA}) = 6.51 \text{ mW}$ PRACTICE PROBLEM 3-5 Using Fig. 3-8, ch 5 V and calculate the new load voltage, current, and und die

Figure 6-10 Set of collector curves

50 µľ 40 µ

20 *µ*A

## DATA SHEETS

GOOD TO KNOW

When displayed on a curve tracer the collector curves in Fig. 6-10 actually have a slight upward slog as  $V_{CI}$  increases. This rise is the result of the base region becomin slightly smaller as  $V_{CI}$  increases. (As  $V_{CI}$  increases, the CB depletion layer widens, thus narrowing the hereal White neurolike hose narios

base.) With a smaller base re-

here are fewer holes availa

tion. Since each cu presents a constant base c e effect looks like an incre

Full and partial component data sheets are provided for many semiconductor devices; key specifications are examined and explained. Complete data sheets of these devices can be found on the Internet.

6 Datas	heet for 1N4001-1N4007 diodes.							
FAIR	CHILD DNDUCTOR*							
	1N4001	- 11	N40	07				
Featur	es							
• Low fo • High s	orward voltage drop. urge current capability.			5				
			E NOR BAND	DO-41	GATHODE			
Gener Absolu	al Purpose Rectifiers	Turdens of	haraisa no	lari				
Symbol	Parameter	Value						Unit
Venu	Peak Repetitive Reverse Voltage	4001 50	4002	4003 200	4004	4005 600	4006 40 800 10	07 00 V
IFUND	Average Rectified Forward Current,				1.0			A
loss.	.375 * lead length @ T <sub>A</sub> = 75°C Non-repetitive Peak Forward Surge				1.0			
.4.044	Current				30			Α.
T	Storage Temperature Range		-55 to +175					°C
T.	Operating Junction Temperature	-55 to +175 °C						
*These ratings	are limiting values above which the serviceability of any semico	nductor de	vice may be	rimpaired.				
Therma		Value				Units		
Therma Symbol	Parameter				3.0			
Therma Symbol	Parameter Power Dissipation	+			3.0			°C/W
Therma Symbol P <sub>0</sub> R <sub>MA</sub>	Power Dissipation Thermal Resistance, Junction to Ambient	-			3.0 50			
Therma Symbol Po Rus Electric	Parameter Power Dissipation Thermal Resistance, Junction to Ambient cal Characteristics T <sub>A</sub> = 25° Curles	s otherwise	e noted		3.0 50			
Therma Symbol Po Rauk Electric Symbol	Power Dissipation Thermal Resistance, Junction to Amblent cal Characteristics T <sub>A</sub> =20 <sup>o</sup> curlex Parameter	s otherwise	e noted		3.0 50 Device			Units
Therma Symbol Po Rus Electric Symbol	Power Dissipation Prover Dissipation Thermal Resistance, Junction to Ambient cal Characteristics Parameter Parameter Exercise 100	s otherwise	e noted	4003	3.0 50 Device	4005	4006 40	Units
Therma Symbol Po Raise Electric Symbol VF	Power Dissipation Power Dissipation Thermal Resistance, Junction to Ambient cal Characteristics Parameter Forward Voltage @ 1.0 A Dissimum Fall and Resease Connect Entit	ss otherwise 4001	e noted	4003	3.0 50 Device 4004 1.1 30	4005	4006 40	Units
Therma Symbol Po Rauk Electric Symbol V <sub>F</sub>	Parameter           Power Dissipation           Thermal Resistance, Junction to Ambient           cal Characteristics           r <sub>a</sub> = 20° curies           Parameter           Forward Voltage @ 1.0 A           Maximum Full Load Reverse Current, Full           Cycle         T <sub>A</sub> = 75°C	s otherwise	e noted	4003	3.0 50 Device 4004 1.1 30	4005	4006 40	07 Units 07 ν
Pp         R           Route         R           Electric         Symbol           Vp         L           L         L           Iq         L	Parameter Power Dissipation Thermal Resistance, Junction to Ambient Thermal Resistance, Junction to Ambient al Characteristics T <sub>x</sub> = 27C units Parameter Forward Voltage @ 1.0 A Maximum Fill Lad Reverse Current, Full Cycle Reverse Current, Full Cycle Reverse Current @ match Vig. T_x = 25°C	4001	e noted 4002	4003	3.0 50 Device 4004 1.1 30 5.0	4005	4006 40	07 Units 07 ν μΑ μΑ
Pip         Pip           Rauk         Electric           Symbol         Vir           U         U           U         U           U         U           U         U           U         U           U         U           U         U	Parameter Power Dissipation Thermal Resistance, Junction to Ambient cal Characteristics T_t_concurrent Farameter Forward Votage @ 1.0 A Maximum Fail Load Reverse Current, Fail Code Carbon Current @ rated Vs, T_c 2700 Vs, Taid Casadance T_a 2100 Vs, Taid Casadance Vs, Taid Casada	4001	e noted	4003	3.0 50 Device 4004 1.1 30 5.0 500 15	4005	4006 40	Unit 07 μΑ μΑ μΑ



Phototransistor versus Photodiode The main difference between a phototimusister and a photodiode is the current. The ains, The same amount of light striking both devices produces  $\beta_{k}$  times more surrent in a phototimusister than in a photodiode. The increased sensitivity of a phototimusiter is a big advantage over that of a phototamsister. Notice the open base: This is the usual way to operate a phototransister. Notice the ensity will variable base return resistor ( $\beta_{1}^{2}$ , 220), but the base is usu-ally left open to get maximum sensitivity to light. The price paid for increased sensitivity is reduced speed. A phototransister tor is more sensitive than a photodiode, but it cannot turn on and off in nanoeconds. The phototransistor is microampress and can avide ho and off in nanoeconds. The phototransistor has typical output currents in milliampress but witches on and off in microaeconds. A typical phototransistor is shown in Fig. 7-22c.

#### Optocoupler

Uptocoupler Figure 7-23a shows an LED driving a phototransistor. This is a much more sen-sitive optocoupler than the LED-photodiode discussed earlier. The idea is straight-forward. Any changes in K produce changes in the LED current, which changes the current through the phototransistor. In turn, itis produces a changing voluces a changing voluce and the input circuit to the output circuit. Studet another way, the common for the input circuit is different from the common for the output circuit. Because of this,

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#### Out-of-Circuit Tests

Out-of-Circuit Tests A transistor is commonly tested using a DMM set to the diode test range. Figure 7-15 shows how an *npn* transistor resembles two back-to-back diodes. Each *pn* junction can be tested for normal forward and reverse biased readings. The collector to estimate rank and be tested and should result in an overrange indi-cation with either DMM polarity connections since a transistor has three leads, there are asis DMM polarity connections result in approximately a 0.7 V reading. Also important to note here is that the base lead is the only connection common to both 0.7 V readings and it requires a (+) polarity connection. This is also shown in Fig. 7-16. *M* prot transistor can be tested using the same technique. As shown in Fig. 7-170. *M* protransistor can be tested using the same technique. As shown in Fig. 7-170. *M* protransistor can be tested using the same technique. As shown in sing the DMM in the diod test range, Fig. 7-18*a* and 7-18*b* show the results for a normal transistor.

the DMM in the chode test range, Fig. /-18a and /-18b show the results to a normal transistor. Many DMMs have a special  $\beta_{ab}$  or  $h_{FZ}$  test function. By placing the transitor's leads into the proper slots, the forward current gain is displayed. This current gain is for a specified base current or collector current and  $V_{CZ}$ . You can check the DMM's manual for the specific test condition. Another way to test transistors is with an ohmmeter. You can beight beyong the collector and the entiter. This should be very high in both directions because the collector and the entiter. This should be very high in both directions because the collector and meinter.



### COMPONENT PHOTOS

Photos of actual electronic devices bring students closer to the device being studied.

## SUMMARY TABLES

Summary Tables have been included at important points within many chapters. Students use these tables as an excellent review of important topics, and as a convenient information resource.





#### 8-5 Other Types of Bias

In this section, we will discuss some other types of bias. A detailed analysis of these types of bias is not necessary because they are rarely used in new designs. But you should at least be aware of their existence in case you see them on a But you should at schematic diagram.

#### Emitter-Feedback Bias

Entitter-Feedback Bias Recall our discussion of base bias (Fig. 8-12a). This circuit is the worst when it comes to setting up a fixed Q point. Why? Since the base current is fixed, the col-lector current varies when the current gain varies, in a circuit like this, the Q point Whome and over the load line with transition replacement and temperature change. Historically, the first attempt at stabilizing the Q point was emitter-feedback bias, shown in Fig. 8-12b. Notice that an entitier resistor has been to increase. More  $I_{20}$  means the stabilizing the Q point was emitter-tering the stabilized bias of the stabilized bias of the stabilized to increase. More  $I_{20}$  means here studing a crease  $R_{20}$ . This results in less  $I_{20}$  which opposes the original increase in  $I_{20}$  value (added because the change in emitter voltage is being for back to the base circuit. Also, the feedback is called *negative* because to oppose the original change in collector current. Emitter-feedback bias never became popular. The movement of the growt is based and large for most applications that have to be mass-produced. Here are the equations for analyzing the emitter-feedback bias:

$I_E = \frac{V_{CC} - V_{BE}}{R_E + R_B / \beta_{dc}}$	(8-17)
$V_E = I_E R_E$	(8-18)
$V_B = V_E + 0.7 V$	(8-19)
$V_C = V_{CC} - I_C R_C$	(8-20)
The intent of emitter-feedback bias is to swamp ou is. $R_F$ should be much greater than $R_0/\beta_{A_0}$ . If this	It the variations in $\beta_{dc}$ ; condition is satisfied.

## COMPONENT TESTING

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Students will find clear descriptions of how to test individual electronic components using common equipment such as digital multimeters (DMMs).

